

FI9-98-205DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re divisional patent application of

Gupta et al.

Serial No.: Not yet assigned

Group Art Unit: Unknown

Filed: Concurrently herewith

Examiner: Unknown

For: PRE-PATTERNED SUBSTRATE LAYERS FOR BEING
PERSONALIZED AS NEEDED

Assistant Commissioner of Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

Sir:

Prior to examination on the merits and calculation of the filing fee, please amend the
above-identified application as follows:

IN THE SPECIFICATION:

Page 1, after line 3, insert the following:

-- Cross-Reference To Related Applications

This application is a division of U.S. Application Serial Number 09/404,510 filed
September 23, 1999. --

IN THE DRAWINGS:

Please substitute the attached formal drawings (3 sheets, containing Figs. 1A-4) for the
drawings which were originally filed with the parent application. The drawings originally filed
with the parent application are attached to a copy of the originally filed specification which are
included herewith.

IN THE CLAIMS:

Please cancel claims 1-18 without prejudice or disclaimer.

Please amend the claims as follows:

19. (Amended) A multi-layer substrate structure comprising:
at least one layer having generic electrical features altered to customize said layer,
wherein said electrical features include vias,
wherein said vias are selectively filled with one of a conducting material and an
insulating material.
22. (Amended) The multi-layer substrate structure in claim 19, further comprising a
second layer similar to said layer and having said generic electrical features altered differently than
said layer to customize said second layer differently than said layer.
23. (Amended) The multi-layer substrate structure in claim 19, wherein said layer is for
being changes into a plurality of differently customized layers.
24. (Amended) The multi-layer substrate structure in claim 19, wherein said layer
includes a generic grid of vias useful with a plurality of differently customized layers.
25. (Amended) The multi-layer substrate structure in claim 19, wherein said layer
includes a generic pattern of wiring useful with a plurality of differently customized layers.

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27. (Amended) The multi-layer substrate structure in claim 26, wherein said insulating caps comprise a screened insulating paste.

Please delete claim 20.

REMARKS

The above changes to the claims have been made to cancel claims being prosecuted in a separate application. This Preliminary Amendment leaves claims 19-28 pending in the present application.

The prior application is assigned of record to International Business Machines Corporation, Armonk, New York, recorded on September 23, 1999, at Reel 010276, Frame 0012.

Early and favorable prosecution on the merits is respectfully requested.